Docket No.: 122.1457

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Nawalage Florence COORAY

Serial No.

Group Art Unit:

Confirmation No.

Filed: June 28, 2001

Examiner:

For: THERMOSETTING FLUORINATED DIELECTRICS AND MULTILAYER CIRCUIT

BOARDS

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

Before calculation of the filing fee for the subject application, please amend the above-identified application as follows:

IN THE CLAIMS:

Please AMEND the pending claims and ADD new claims * in accordance with the following:

- 3. (AS ONCE AMENDED HEREIN) A dielectric film obtained by heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1.
- 4. (AS ONCE AMENDED HEREN) A process for producing a dielectric film comprising heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1.
- 6. (AS NEW HEREIN) A dielectric film obtained by heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 2.
- 7. (AS NEW HEREIN) A process for producing a dielectric film comprising heat curing a thermally curable fluorinated o-aminophenologolymer or oligomer according to claim 2.

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